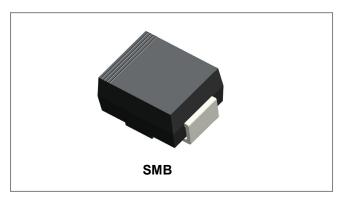






RS2A-RS2M SURFACE MOUNT SUPER FAST RECTIFIER



Features

- Fast switching for high efficiency
- Low leakage current
- · High forward surge capability
- Solder dip 260 ° C, 40 s
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC
- This is a Pb Free Device
- All SMC parts are traceable to the wafer lot
- · Additional testing can be offered upon request

Circuit Diagram



Mechanical Data

- Case: SMB molded plastic body
- Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode end
- Mounting Position: AnyWeight: 0.09 grams

Maximum Ratings and Electrical Characteristics @TA=25°C unless otherwise specified

Type Number	Symbol	RS2A	RS2B	RS2D	RS2G	RS2J	RS2K	RS2M	Units
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _{DC}	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	V _{RMS}	35	70	140	280	420	560	700	V
Average forward rectified output current @T _A = 90°C	Io				2.0				А
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	50			А				
Forward Voltage @I _F =2.0A	V _F				1.3				V
Peak Reverse Current @T _A = 25°C At Rated DC Blocking Voltage @T _A = 100°C	I _{RM}	5.0 50			μA				
Maximum Reverse Recovery Time (Note 1)	Trr	150		250	500		ns		
Typical Junction Capacitance (Note 2)	CJ	50				pF			
Typical Thermal Resistance (Note 3)		55				°C/W			
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150				°C			

Note: 1. Measured with I_F =0.5A, I_R =1.0A, I_{rr} =0.25A,

- 2. Measured at 1.0 MHZ and applied reverse voltage of 4.0 VDC
- 3. Thermal resistance from junction to ambient at 0.375"(9.5mm)lead length, P.C.B. mounted
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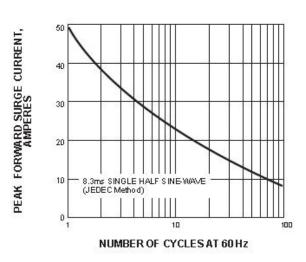


Ratings and Characteristics Curves

FIG.1-FORWARD CURRENT DERATING CURVE

INSTANTANEOUS FORWARD CURRENT, AMPERES

FIG.2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT



AMBIENT TEMPERATURE,°C

100

125

150

175

FIG.3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

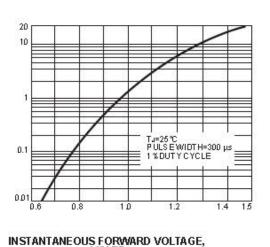
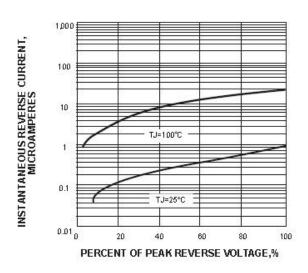


FIG.4-TYPICAL REVERSE CHARACTERISTICS



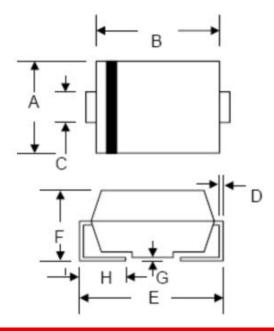
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Mechanical Dimensions SMB



CVMPOL	Millir	meters	Inches		
STMBOL	SYMBOL Min. N		Min.	Max.	
А	3.30	3.94	0.130	0.155	
В	4.06	4.70	0.160	0.185	
С	1.80	2.20	0.071	0.087	
D	0.152	0.305	0.006	0.012	
Е	4.80	5.59	0.189	0.220	
F	2.10	2.60	0.083	0.102	
G	0.051	0.203	0.002	0.008	
Н	0.76	1.52	0.030	0.060	

Ordering Information

Device	Package	Shipping		
RS2A-RS2M	SMB(Pb-Free)	3000pcs / reel		

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram



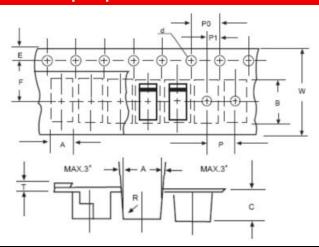
Where XXXXX is YYWWL

RS2A = Type Number SSG = SSG YY = Year WW = Week L = Lot Number

Cautions: Molding resin

Epoxy resin UL:94V-0

Carrier Tape Specification SMB



SYMBOL	Millimeters			
	Min.	Max.		
Α	3.99	4.19		
В	5.72	5.92		
С	3.23	3.43		
d	1.40	1.60		
E	1.40	1.60		
F	5.60	5.70		
Р	7.90	8.10		
P0	3.90	4.10		
P1	1.90	2.10		
Т	-	0.60		
W	11.80	12.20		

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